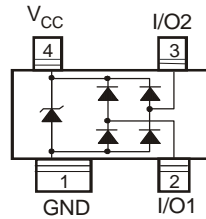


2 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY
Features

- IEC 61000-4-2 (ESD): Air $\pm 15\text{kV}$, Contact $\pm 8\text{kV}$
- 2 Channels of ESD Protection
- Low Channel Input Capacitance of 1.0pF Typical
- Typically Used at High Speed Ports such as USB 2.0, IEEE1394, Serial ATA, DVI, HDMI, PCI
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT143
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Weight: 0.009 grams (approximate)

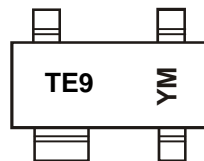


Device Schematic

Ordering Information (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DRTR5V0U2SR-7	AEC-Q101	TE9	7	8	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


TE9 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: A = 2013)
 M = Month (ex: 9 = September)

Date Code Key

Year	2013	2014	2015	2016	2017	2018	2019
Code	A	B	C	D	E	F	G

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	I_{PP}	5	A	8/20 μs , Per Figure 3
ESD Protection – Contact Discharge	$V_{ESD_Contact}$	± 8	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V_{ESD_Air}	± 15	kV	Standard IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	400	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	310	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V_{RWM}	—	—	5.5	V	—
Channel Leakage Current (Note 6, 7)	I_R	—	1	100	nA	$V_R = 3\text{V}$
Reverse breakdown voltage	V_{BR}	6.0	—	9.0	V	$I_R = 1\text{mA}$, from pin 4 to pin 1
Forward Voltage (Note 7)	V_F	—	0.8	—	V	$I_F = 8\text{mA}$
Dynamic Resistance (Note 7)	R_{DYN}	—	0.9	—	Ω	$I_{PP} = 1\text{A}$, $t_p = 8/20\mu\text{s}$
I/O to GND Capacitance (Note 7)	$C_{(I/O-GND)}$	—	1.0	1.5	pF	$V_{(I/O-GND)} = 0\text{V}$, $f = 1\text{MHz}$

- Notes:
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 - Short duration pulse test used to minimize self-heating effect.
 - Measured from pin 2 or pin 3 to GND.
 - For information on the impact of Diodes' USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: http://www.diodes.com/destools/appnote_dnote.html.

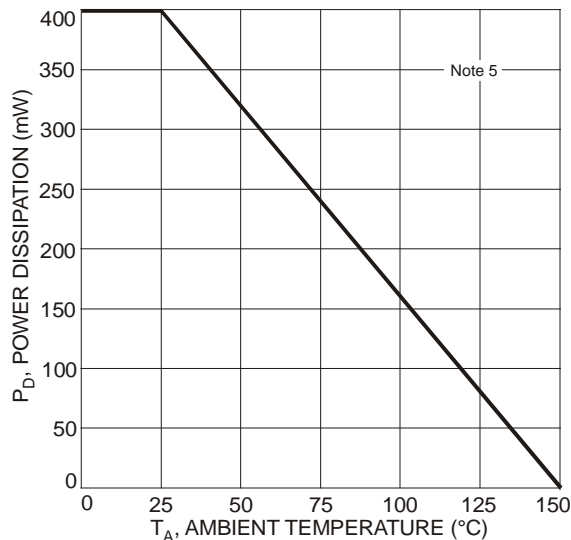


Figure 1 Power Dissipation vs. Ambient Temperature

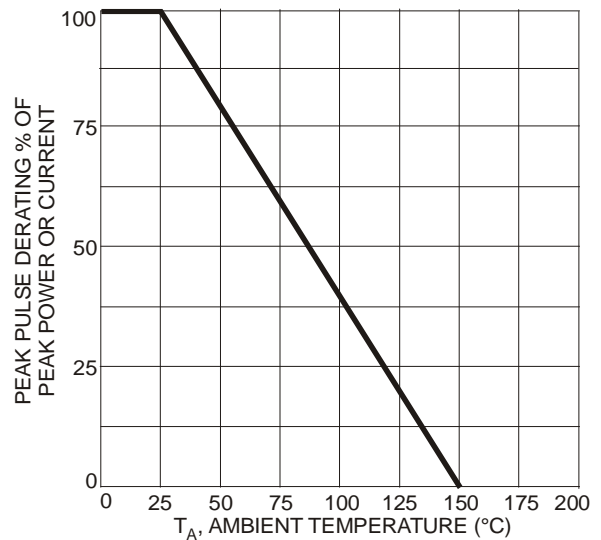


Figure 2 Pulse Derating Curve

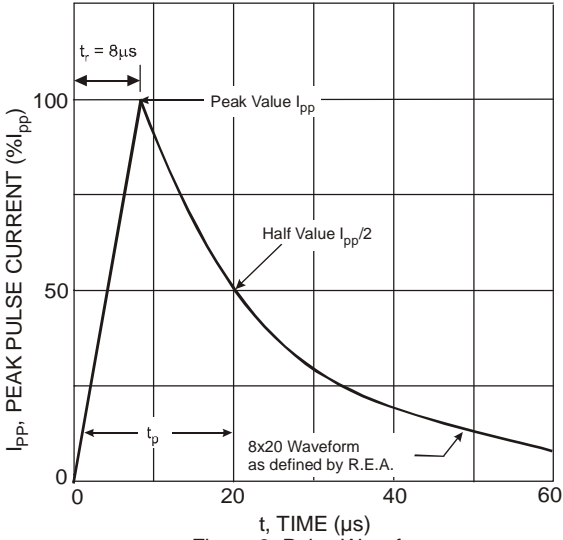


Figure 3 Pulse Waveform

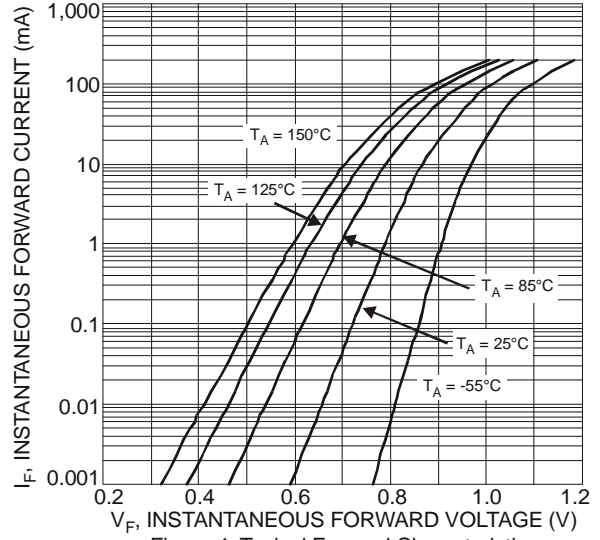


Figure 4 Typical Forward Characteristics

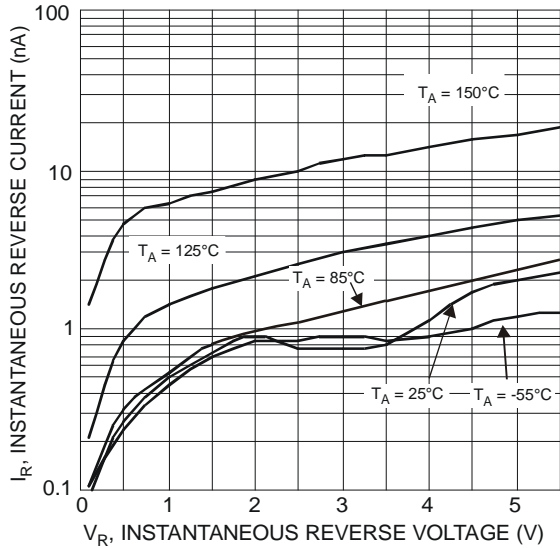


Figure 5 Typical Reverse Characteristics

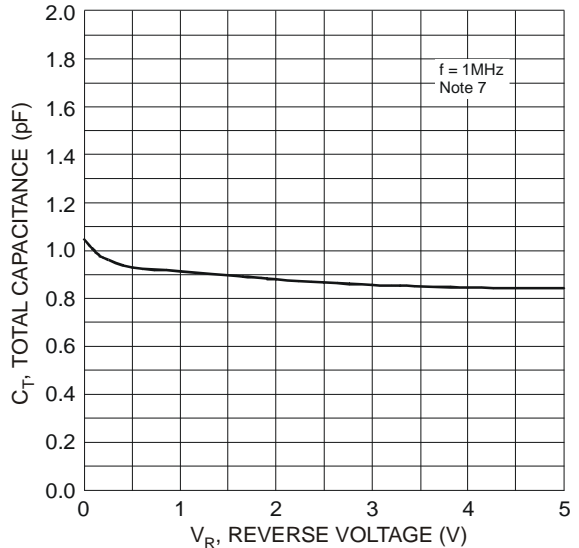
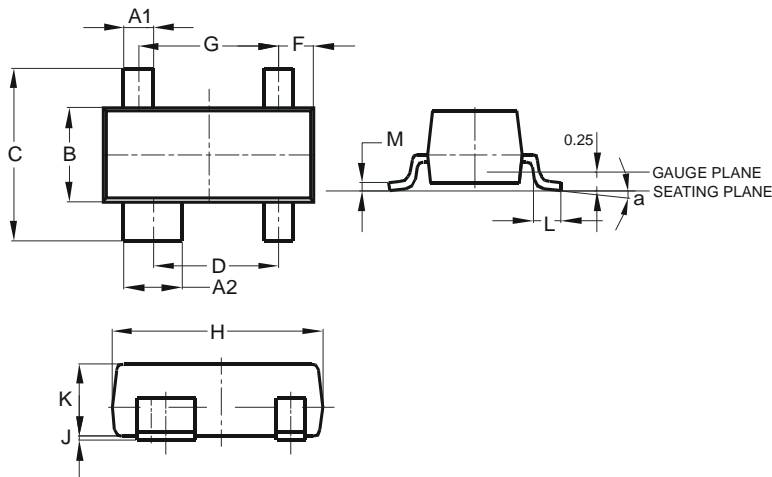


Figure 6 Typical Total Capacitance vs. Reverse Voltage

Package Outline Dimensions

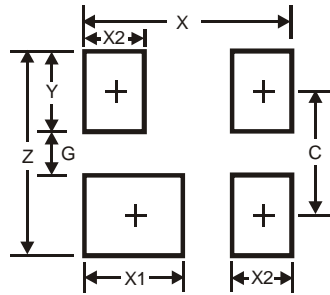
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT143			
Dim	Min	Max	Typ
A1	0.37	0.51	0.400
A2	0.77	0.93	0.800
B	1.20	1.40	1.30
C	2.28	2.48	2.38
D	1.58	1.83	1.72
F	0.45	0.60	0.49
G	1.78	2.03	1.92
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.89	1.00	-
L	0.46	0.60	0.50
M	0.085	0.18	0.11
a	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.70
G	1.30
X	2.50
X1	1.0
X2	0.60
Y	0.70
C	2.0

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